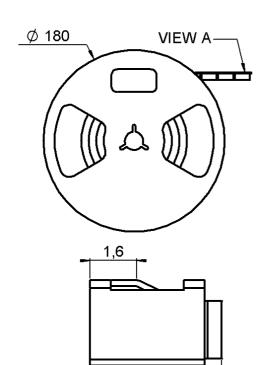
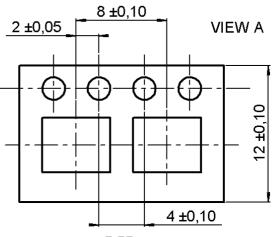
R107.303.040 Series : UMP

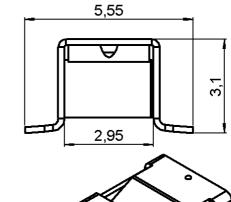
REEL 100

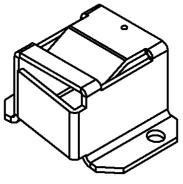


3,8

4,35









All dimensions are in mm.

_	COMPONENTS	MATERIALS	PLATINGS (μm)	
-	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BERYLLIUM COPPER	GOLD 0.2 OVER NICKEL 2	

Issue: 0417 B



R107.303.040

REEL 100

Series: UMP

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance $\mathbf{50} \Omega$ Frequency $\mathbf{0-6} \text{ GHz}$

VSWR 1.05 + 0.030 x F(GHz) Maxi Insertion loss NA $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz)) dB Maxi

Voltage rating 100 Veff Maxi Dielectric withstanding voltage 350 Veff mini Insulation resistance 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -40/+125 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end - N mini
Axial force – Opposite end - N mini
Torque - N.cm mini

Recommended torque

Mating - N.cm
Panel nut - N.cm

Mating life 50 Cycles mini

Weight **0.060** g

Issue: 0417 B



REEL 100

R107.303.040

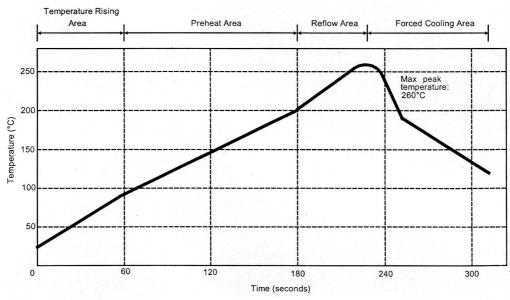
Series: UMP

SOLDER PROCEDURE OF UMP RECEPTABLE IN INDUSTRIAL ENVIRONMENT

- 1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- The cleaning of printed circuit boards is not obliged.
- Verification of solder joints and position of the component by visual inspection.

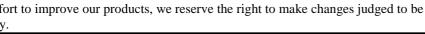
NOTE: The UMP receptacle and the UMP plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0417 B





R107.303.040

REEL 100

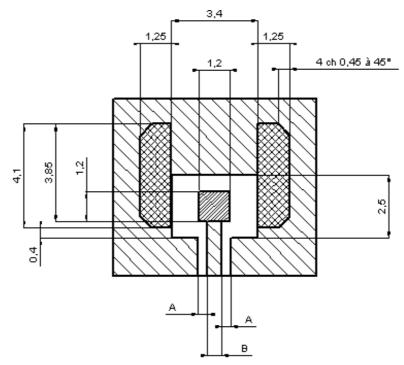
Series: UMP

UMP SERIES INFORMATION

PCB

COPLANAR LINE

Ground and signal are on the same side The material of PCB is glass is glass-epoxy Composite.



Gold over nickel for solder paste

Gold over nickel contact area free of any surface contaminant

Ground + varnish

APPLICATION 75Ω

WITH B = 0.55mm

777777 = 0,00111111	
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,57
1,0	0,45
1,2	0,41
1,6	0,37

APPILCATION 50Ω

WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,183
1,0	0,190
1,2	0,195
1,6	0,20

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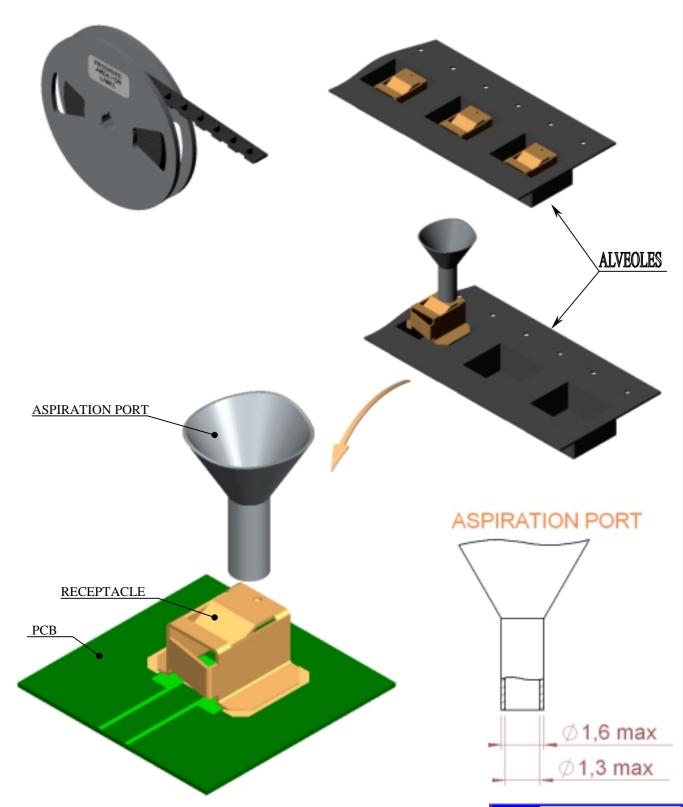


REEL 100

R107.303.040

Series: UMP

UMP SERIES INFORMATION



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In the effort to improve our products, we reserve the right to make changes judged to be

necessary.



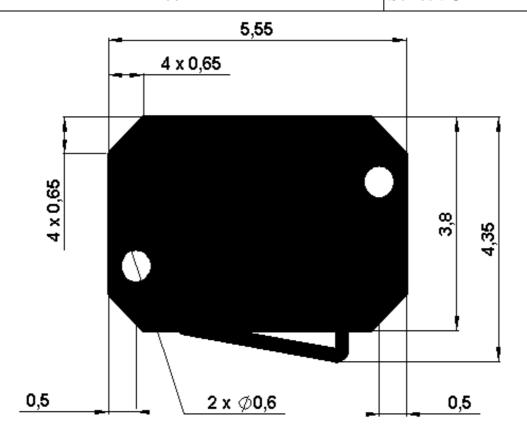
6/9

RIGHT ANGLE H3 RECEPTACLE SMT TYPE

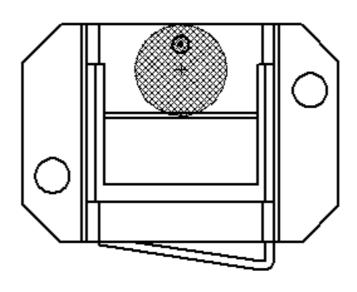
Series : UMP

R107.303.040

REEL 100



SHADOW FOR VIDEO CAMERA





Issue: 0417 B

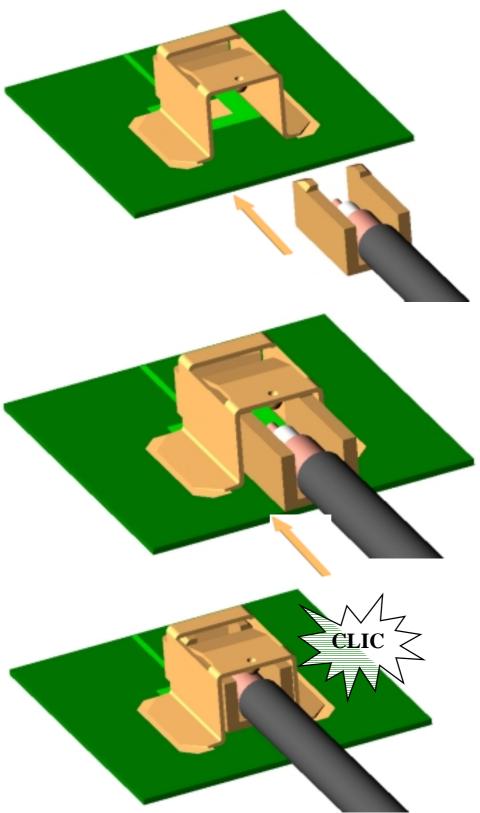


REEL 100

R107.303.040

Series: UMP

UMP CONNECTING NOTE



Issue: 0417 B

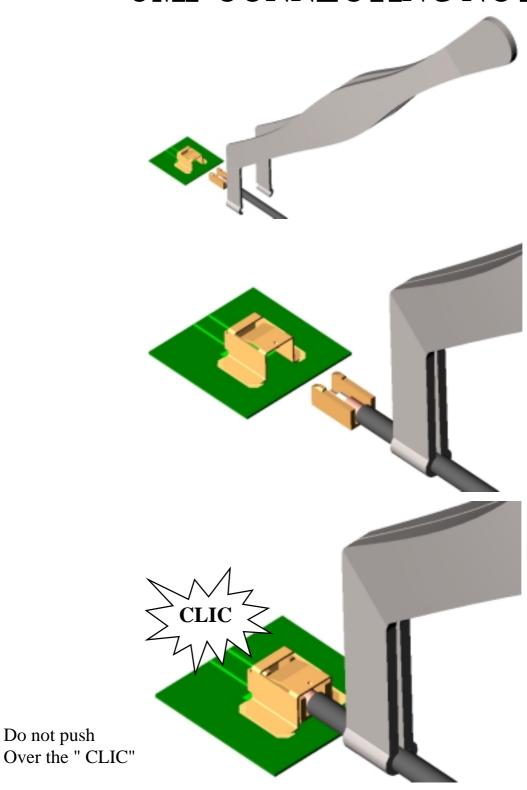


REEL 100

R107.303.040

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UMP CONNECTING NOTE



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Do not push

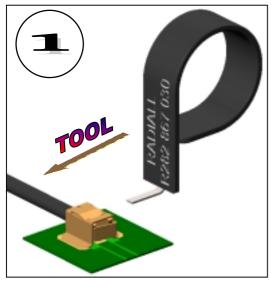


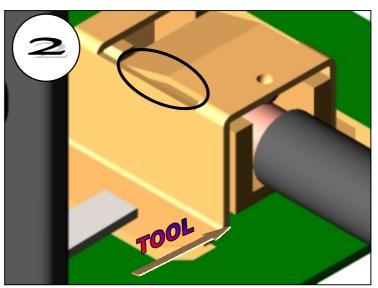
REEL 100

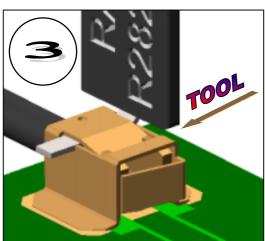
R107.303.040

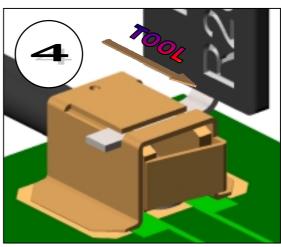
Series: UMP

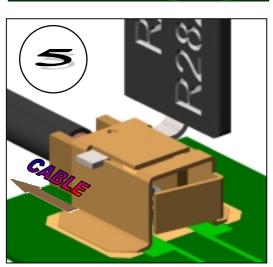
UMP DISCONNECTING NOTE

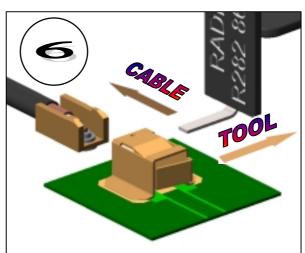












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